

# 20-Channel Serial-Input Vacuum Fluorescent Display Driver for Anode or Grid

# **Features**

- HVCMOS<sup>®</sup> Technology for High Performance
- · Operating Voltage of up to 80V
- · High-speed Source Driver
- 5V CMOS Logic Circuitry
- Up to 5 MHz Data Input Rate
- · Excellent Noise Immunity
- · Flexible High-voltage Supplies

# **Applications**

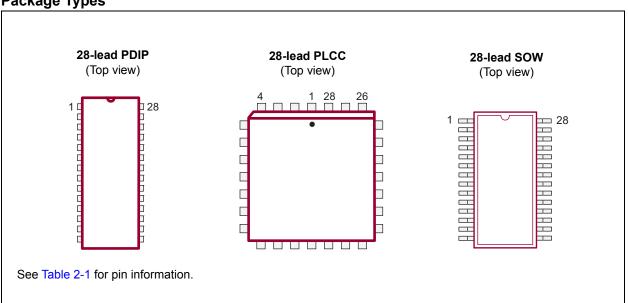
· Display Driver

# **General Description**

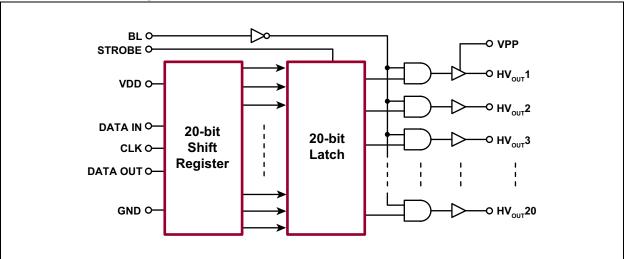
The HV5812 is a 20-channel serial-input vacuum fluorescent display driver. It combines a 20-bit CMOS shift register, data latches and control circuitry with high-voltage MOSFET outputs. The HV5812 is primarily designed for vacuum fluorescent displays.

The CMOS shift register and latches allow direct interfacing with microprocessor-based systems. Data input rates are typically over 5 MHz with 5V logic supply. Especially useful for interdigit blanking, the blanking input disables the output source drives and turns on the sink drivers. Using with TTL may require external pull-up resistors to ensure an input logic high.

# **Package Types**



# **Functional Block Diagram**



# 1.0 ELECTRICAL CHARACTERISTICS

# **Absolute Maximum Ratings†**

Supply Voltage, V <sub>DD</sub> Supply Voltage, V <sub>PP</sub>	0.5V to +7.5V 0.5V to +90V
Logic Input Levels	–0.3V to V <sub>DD</sub> +0.3V
Maximum Operating Junction Temperature	+125°C
Storage Temperature	55°C to +150°C
Power Dissipation:	
28-lead PDIP	2000 mW
28-lead PLCC	1900 mW
28-Lead SOW	1700 mW

† Notice: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

# RECOMMENDED OPERATING CONDITIONS

Parameter	Sym.	Min.	Тур.	Max.	Unit	Conditions
Supply Voltage	$V_{DD}$	4.5	_	5.5	V	
Supply Voltage	$V_{PP}$	20	_	80	V	
Operating Junction Temperature	TJ	-40	_	+125	°C	

# DC ELECTRICAL CHARACTERISTICS

Electrical Specifications: Ove	r recom	mended	operatir	ng condit	ions; T <sub>A</sub>	= 25°C	unless otherwise indicated.
Parameter	Sy	/m.	Min.	Тур.	Max.	Unit	Conditions
Output Leakage Current	I	SS		<b>-</b> 5	-15	μΑ	V <sub>OUT</sub> = 0V, T <sub>A</sub> = +70°C
		HV <sub>OUT</sub>	78	78.5		V	$I_{OUT} = -25 \text{ mA}, V_{PP} = 80V,$ $T_{J} = +25^{\circ}\text{C}$
High-level Output	$V_{OH}$		77	78		V	$I_{OUT}$ = -25 mA, $V_{PP}$ = 80V, $T_{J}$ = +125°C
		DATA OUT	4.5	4.7	1	٧	I <sub>OUT</sub> = –200 μA, V <sub>DD</sub> = 5V
			1	1.5	3		$I_{OUT} = 1 \text{ mA}, T_J = +25^{\circ}\text{C}, V_{DD} = 5\text{V}$
Low-level Output	V <sub>OL</sub>	HV <sub>OUT</sub>	_	2.3	4	V	I <sub>OUT</sub> = 1 mA, T <sub>J</sub> = +125°C, V <sub>DD</sub> = 5V
		DATA OUT	_	200	250	٧	I <sub>OUT</sub> = +200 μA, V <sub>DD</sub> = 5V
Output Pull-down Current	I <sub>S</sub>	INK	2	3.5	_	mA	$V_{OUT}$ = 5V to $V_{PP}$ , $V_{DD}$ = 5V
High-level Logic Input Voltage	٧	'IH	3.5		5.3	٧	V <sub>DD</sub> = 5V
Low-level Logic Input Voltage	\	/ <sub>IL</sub>	-0.3		0.8	٧	
High-level Logic Input Current	I	IH		0.05	0.5	μΑ	$V_{IN} = V_{DD}, V_{DD} = 5V$
Low-level Logic Input Current	I	IL		-0.05	-0.5	μΑ	V <sub>IN</sub> = 0.8V, V <sub>DD</sub> = 5V
Quiescent V <sub>DD</sub> Supply	l_		_	100	300	μA	All outputs high, V <sub>DD</sub> = 5V
Current	טי	DQ	_	100	300	μΛ	All outputs low, V <sub>DD</sub> = 5V
Quiescent V <sub>PP</sub> Supply Current	1		_	10	100	μA	All outputs high, no load
Quicocont Vpp Oupply Ourient	ıμ	PQ	_	10	100	μΛ	All outputs low, no load

# HV5812

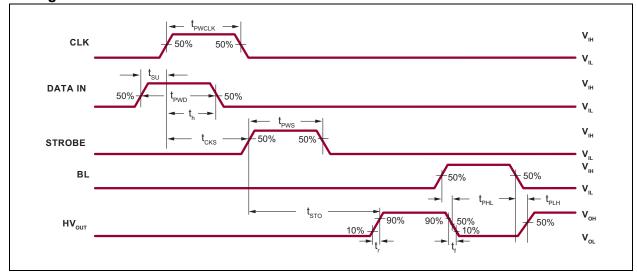
# **AC ELECTRICAL CHARACTERISTICS**

Electrical Specifications: Over	recommen	ded oper	ating con	ditions; T	A = 25°C	unless otherwise indicated.
Parameter	Sym.	Min.	Тур.	Max.	Unit	Conditions
Planking to Output Dalay	t <sub>PHL</sub>	_	2000	_	no	C = 30 pF F00/ to F00/ \/ =5\/
Blanking to Output Delay	t <sub>PLH</sub>	1	1000	_	ns	$C_L = 30 \text{ pF}, 50\% \text{ to } 50\%, V_{DD} = 5V$
Output Fall Time	t <sub>r</sub>	-	1450	_	ns	$C_L = 30 \text{ pF}, 90\% \text{ to } 10\%, V_{DD} = 5V$
Output Rise Time	t <sub>f</sub>		650	_	ns	$C_L = 30 \text{ pF}, 10\% \text{ to } 90\%, V_{DD} = 5V$
Data Set-up Time	t <sub>SU</sub>	75	_		ns	See Timing Waveforms.
Data Hold Time	t <sub>H</sub>	75	_		ns	See Timing Waveforms.
Minimum Data Pulse Width	t <sub>PWD</sub>	150	_	_	ns	See Timing Waveforms.
Minimum Clock Pulse Width	t <sub>PWCLK</sub>	150	_		ns	See Timing Waveforms.
Minimum Time between Clock Activation and Strobe	t <sub>CKS</sub>	300	_	_	ns	See Timing Waveforms.
Minimum Strobe Pulse Width	t <sub>PWS</sub>	100	_	_	ns	SeeTiming Waveforms.
Typical Time between Strobe Activation and Output Transition	t <sub>STO</sub>	_	500	_	ns	See Timing Waveforms.
Maximum Clock Frequency	£		8		MLI-	T <sub>J</sub> = +25°C, V <sub>DD</sub> = 5V
	f <sub>CLK</sub>	_	5	_	MHz	T <sub>J</sub> = +125°C, V <sub>DD</sub> = 5V

# **TEMPERATURE SPECIFICATIONS**

Parameter	Sym.	Min.	Тур.	Max.	Unit	Conditions
TEMPERATURE RANGE						
Operating Junction Temperature	$T_J$	<del>-4</del> 0	_	+125	°C	
Storage Temperature	T <sub>S</sub>	-55	_	+150	°C	
PACKAGE THERMAL RESISTA	NCE					
28-lead PDIP	$\theta_{JA}$		43		°C/W	
28-lead PLCC	$\theta_{JA}$	_	48	_	°C/W	
28-lead SOW	$\theta_{JA}$	_	55	_	°C/W	

# **Timing Waveforms**



# 2.0 PIN DESCRIPTION

The details on the pins of HV5812 28-lead PDIP, 28-lead PLCC and 28-lead SOW are listed on Table 2-1. Refer to **Package Types** for the location of pins.

TABLE 2-1: PIN FUNCTION TABLE

Pin Number	Pin Name	Description
1	VPP	High-voltage power rail
2	Data Out	Serial data output. Data output for cascading to the data input of the next device.
3	HV <sub>OUT</sub> 20	High-voltage output
4	HV <sub>OUT</sub> 19	High-voltage output
5	HV <sub>OUT</sub> 18	High-voltage output
6	HV <sub>OUT</sub> 17	High-voltage output
7	HV <sub>OUT</sub> 16	High-voltage output
8	HV <sub>OUT</sub> 15	High-voltage output
9	HV <sub>OUT</sub> 14	High-voltage output
10	HV <sub>OUT</sub> 13	High-voltage output
11	HV <sub>OUT</sub> 12	High-voltage output
12	HV <sub>OUT</sub> 11	High-voltage output
13	BLANKING	Blank
14	GND	Logic and high-voltage ground
15	CLOCK	Data shift register clock
16	STROBE	Strobe
17	HV <sub>OUT</sub> 10	High-voltage output
18	HV <sub>OUT</sub> 9	High-voltage output
19	HV <sub>OUT</sub> 8	High-voltage output
20	HV <sub>OUT</sub> 7	High-voltage output
21	HV <sub>OUT</sub> 6	High-voltage output
22	HV <sub>OUT</sub> 5	High-voltage output
23	HV <sub>OUT</sub> 4	High-voltage output
24	HV <sub>OUT</sub> 3	High-voltage output
25	HV <sub>OUT</sub> 2	High-voltage output
26	HV <sub>OUT</sub> 1	High-voltage output
27	Data In	Serial data input
28	VDD	Low-voltage logic power rail

# 3.0 FUNCTIONAL DESCRIPTION

Follow the steps below to power up and power down the HV5812:

# POWER-UP AND POWER-DOWN SEQUENCE

	Power-up		Power-down
Step	Description	Step	Description
1	Connect ground.	1	Remove V <sub>PP</sub> .
2	Apply V <sub>DD</sub> .	2	Remove all inputs.
3	Set all inputs (Data, CLK, etc.) to a known state	3	Remove V <sub>DD</sub> .
4	Apply V <sub>PP</sub> (Note 1)	4	Disconnect ground.

**Note 1:** The V<sub>PP</sub> should not drop below V<sub>DD</sub> during operation.

# **FUNCTION TABLE (Note 1)**

Serial	Clock	SI	hift R	egister Cont	ents	Serial	Strobe		Lat	ch Contents			Output Contents					
Data Input	Input	I <sub>1</sub>	l <sub>2</sub>	I <sub>3</sub> I <sub>N-1</sub>	I <sub>N</sub>	Data Output	Input	I <sub>1</sub>	l <sub>2</sub>	I <sub>3</sub> I <sub>N-1</sub>	I <sub>N</sub>	Blanking	I <sub>1</sub>	l <sub>2</sub>	I <sub>3</sub> I <sub>N-1</sub>	I <sub>N</sub>		
Н	L to H	Н	R <sub>1</sub>	R <sub>2</sub> R <sub>N-2</sub>	R <sub>N-1</sub>	R <sub>N-1</sub>	_	_	_	ı	_	_	_	_	ı	_		
L	L to H	L	$R_1$	R <sub>2</sub> R <sub>N-2</sub>	R <sub>N-1</sub>	R <sub>N-1</sub>		ı	1	I	_	_	ı			_		
X	H to L	$R_1$	$R_2$	R <sub>3</sub> R <sub>N-1</sub>	$R_N$	R <sub>N</sub>		ı	1	I	_	_	ı			_		
_	_	Χ	Χ	XX	Х	Х	L	R <sub>1</sub>	$R_2$	R <sub>3</sub> R <sub>N-1</sub>	$R_N$	_	ı		ı	_		
_	_	P <sub>1</sub>	P <sub>2</sub>	P <sub>3</sub> P <sub>N-1</sub>	$P_N$	$P_N$	Н	P <sub>1</sub>	$P_2$	P <sub>3</sub> P <sub>N-1</sub>	$P_{N}$	L	P <sub>1</sub>	P <sub>2</sub>	P <sub>3</sub> P <sub>N-1</sub>	$P_{N}$		
_	_			_	_	_	_	Х	Χ	XX	Х	Н	L	L	LL	L		

**Note 1:** L = Low logic level

H = High logic level

X = Irrelevant

P = Present state

R = Previous state

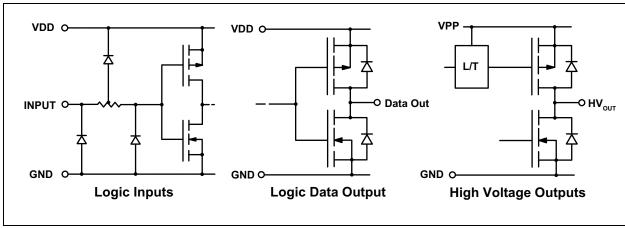
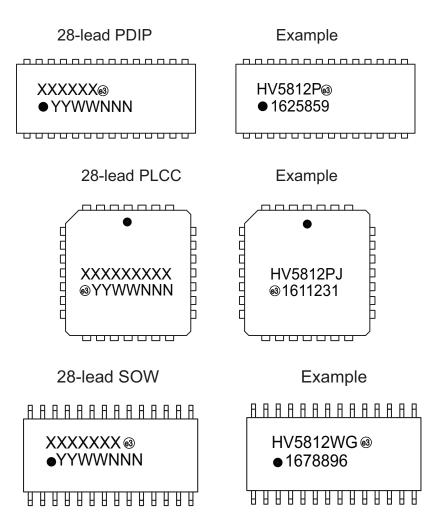


FIGURE 3-1: IO Circuits.

# 4.0 PACKAGE MARKING INFORMATION

# 4.1 Packaging Information

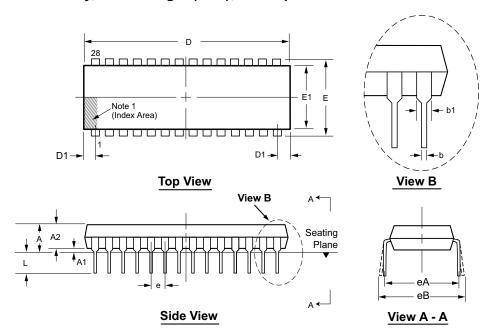


Legend: XX...X Product Code or Customer-specific information
Year code (last digit of calendar year)
YY Year code (last 2 digits of calendar year)
WW Week code (week of January 1 is week '01')
NNN Alphanumeric traceability code
Pb-free JEDEC® designator for Matte Tin (Sn)
\* This package is Pb-free. The Pb-free JEDEC designator (@3)
can be found on the outer packaging for this package.

**Note**: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for product code or customer-specific information. Package may or not include the corporate logo.

# 28-Lead PDIP (.600in Row Spacing) Package Outline (P)

1.565x.580in body, .250in height (max), .100in pitch



Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

1. A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.

Symbo	ol	Α	A1	A2	b	b1	D	D1	Е	E1	е	eA	eВ	L
	MIN	.140*	.015	.125	.014	.030	1.380	.065 <sup>†</sup>	.590 <sup>†</sup>	.485			.600*	.115
Dimension (inches)	NOM	-	-	-	-	-	-	-	-	-	.100 BSC	.600 BSC	-	-
()	MAX	.250	.055*	.195	.023 <sup>†</sup>	.070	1.565	.085*	.625	.580			.700	.200

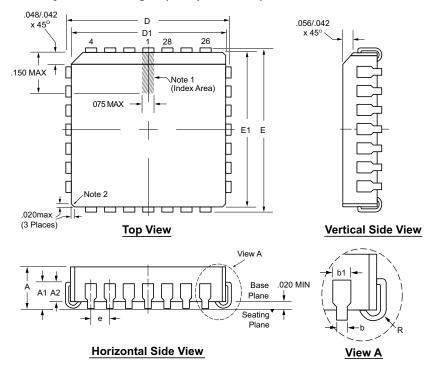
JEDEC Registration MS-011, Variation AB, Issue B, June, 1988.

\* This dimension is not specified in the JEDEC drawing.

† This dimension differs from the JEDEC drawing.

Drawings not to scale.

# 28-Lead PLCC Package Outline (PJ) .453x.453in. body, .180in. height (max), .050in. pitch



Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

- A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or
- a printed indicator. Actual shape of this feature may vary.

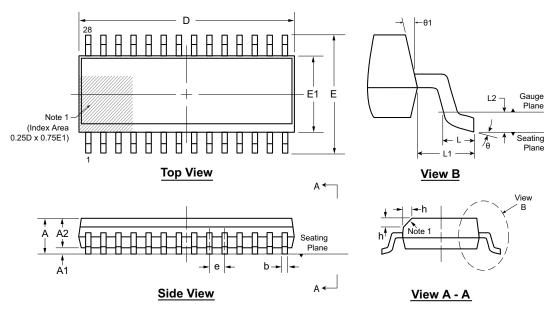
Symbo	l	Α	A1	A2	b	b1	D	D1	E	E1	е	R
	MIN	.165	.090	.062	.013	.026	.485	.450	.485	.450		.025
Dimension (inches)	NOM	.172	.105	-	-	-	.490	.453	.490	.453	.050 BSC	.035
()	MAX	.180	.120	.083	.021	.032	.495	.456	.495	.456		.045

JEDEC Registration MS-018, Variation AB, Issue A, June, 1993.

Drawings not to scale.

# 28-Lead SOW (Wide Body) Package Outline (WG)

17.90x7.50mm body, 2.65mm height (max), 1.27mm pitch



Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

# Note:

1. A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.

Symbo	ol	Α	A1	A2	b	D	Е	E1	е	h	L	L1	L2	θ	θ1
	MIN	2.15*	0.10	2.05	0.31	17.70*	9.97*	7.40*		0.25	0.40			0°	5°
Dimension (mm)	NOM	-	-	-	-	17.90	10.30	7.50	1.27 BSC	-	-	1.40 REF	0.25 BSC	1	-
. ,	MAX	2.65	0.30	2.55*	0.51	18.10*	10.63*	7.60*		0.75	1.27			8°	15°

JEDEC Registration MS-013, Variation AE, Issue E, Sep. 2005.

Drawings are not to scale.

<sup>\*</sup> This dimension is not specified in the JEDEC drawing.



NOTES:

# APPENDIX A: REVISION HISTORY

# **Revision A (October 2016)**

- Converted Supertex Doc# DSFP-HV5812 to Microchip DS20005629A
- Changed the packaging quantity of 28-lead PLCC (PJ M904) from 500/Reel to 750/Reel and 28-lead SOW (WG) from 1000/Reel to 1600/Reel
- Made minor text changes throughout the document

# PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

<u> </u>	-	<u> </u>		ΕX	amples:	
Package Options		 Environmental Media Type		a)	HV5812P-G:	20-Channel Serial-Input Vacuum Fluorescent Display Driver for Anode or Grid, 28-lead PDIP.
HV5812	=	20-Channel Serial-Input Vacuum Fluorescent Display Driver for Anode or Grid		b)	HV5812PJ-G:	13/Tube 20-Channel Serial-Input Vacuum Fluorescent Display Driver for Anode or Grid, 28-lead PLCC, 38/Tube
D	_	28 load PDIP		c)	HV5812PJ-G-M904:	20-Channel Serial-Input Vacuum
=						Fluorescent Display Driver for Anode or Grid, 28-lead PLCC,
	=					750/Reel
G	=	Lead (Pb)-free/RoHS-compliant Package		d)	HV5812WG-G:	20-Channel Serial-Input Vacuum Fluorescent Display Driver for Anode or Grid, 28-lead SOW, 1600/Reel
(blank)	=	13/Tube for a P Package				
	=	38/Tube for a PJ Package				
	=	1600/Reel f or a WG Package				
M904	=	750/Reel for a PJ Package				
	Package Options  HV5812  P PJ WG G (blank)	Package Options  HV5812 =  P = PJ = WG =  G = (blank) = = = =	Package Options  Environmental Media Type  HV5812 = 20-Channel Serial-Input Vacuum Fluorescent Display Driver for Anode or Grid  P = 28-lead PDIP PJ = 28-lead PLCC WG = 28-lead SOW  G = Lead (Pb)-free/RoHS-compliant Package  (blank) = 13/Tube for a P Package = 38/Tube for a PJ Package = 1600/Reel f or a WG Package	Package Options  Environmental Media Type  HV5812 = 20-Channel Serial-Input Vacuum Fluorescent Display Driver for Anode or Grid  P = 28-lead PDIP PJ = 28-lead PLCC WG = 28-lead SOW  G = Lead (Pb)-free/RoHS-compliant Package  (blank) = 13/Tube for a P Package = 38/Tube for a PJ Package = 1600/Reel f or a WG Package	Package Options  Environmental Media Type  a)  HV5812 = 20-Channel Serial-Input Vacuum Fluorescent Display Driver for Anode or Grid  P = 28-lead PDIP PJ = 28-lead PLCC WG = 28-lead SOW  G = Lead (Pb)-free/RoHS-compliant Package (blank) = 13/Tube for a P Package = 38/Tube for a PJ Package = 1600/Reel f or a WG Package	Package Options  Environmental Media Type  a) HV5812P-G:  b) HV5812PJ-G:  b) HV5812PJ-G:  b) HV5812PJ-G:  c) HV5812PJ-G:  c) HV5812PJ-G-M904:  c) HV5812PJ-G-M904:  d) HV5812PJ-G-M904:  c) HV5812PJ-G-M904:  d) HV5812WG-G:  d) HV5812WG-G:

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